

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L10	1	"6813121".pn.	US-PGPUB; USPAT	OR	OFF	2005/06/15 10:23
L26	23	(US-20020055307-\$ or US-20020093773-\$ or US-20030053265-\$ or US-20030058587-\$ or US-20040004788-\$ or US-20040008455-\$ or US-20040027731-\$ or US-20040062152-\$ or US-20040095691-\$ or US-20050024782-\$).did. or (US-5491600-\$ or US-5680282-\$ or US-5883764-\$ or US-6176005-\$ or US-6209193-\$ or US-6219207-\$ or US-6501626-\$ or US-6570743-\$ or US-6760966-\$ or US-6783874-\$ or US-6785101-\$ or US-6798622-\$ or US-6813121-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/06/15 11:58
S1	251	(360/322).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 21:44
S2	258	(360/313).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 21:44
S3	1466	(360/110).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 21:45
S4	1966	S1 S2 S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:18
S5	29171	second adj electrodes!	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:18
S6	3473	second adj leads!	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:18

S7	273591	hardness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:18
S8	711	polishing near2 resistance	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:19
S9	9225	additional with conductors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:19
S10	177989	("360"/\$ "369"/\$ "720"/\$ 29/603\$).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:19
S11	190	S5 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:19
S12	353	S6 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:19
S13	19	S8 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:19
S14	96	S9 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:19
S15	653	S11 S12 S13 S14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:51
S16	2290	S7 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:20

S17	10	S16 and (S11 S12 S14)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:33
S18	193283	bilayer multilayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:33
S19	4743302	lead electrode contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:33
S20	6329	S18 near3 S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:33
S21	127	S10 and S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:33
S22	549554	etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:51
S23	279212	polish\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:52
S24	4845654	resist\$5 rate rates	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:52
S25	88104	(S22 S23) near2 S24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:52
S26	10792	S19 with S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:53

S27	1037376	recess\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:53
S28	399	S26 same S27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:53
S29	89	S10 and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 22:53